



BOARD CHARACTERISTICS

Copper Layer Count: 4

Board Thickness: 0.7800 mm

Board overall dimensions: 19.0500 mm x 7.8740 mm

Min track/spacing: 0.1270 mm / 0.1270 mm

Min hole diameter: 0.1016 mm

Copper Finish: ENIG

Impedance Control: No

Castellated pads: Yes

Plated Board Edge: Yes

Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR408-HR	0.11 mm	FR4 natural	3.69	0.0091
In1.Cu	copper		0.035 mm		1	0
Dielectric 2	core	FR408-HR	0.4 mm	FR4 natural	3.69	0.0091
In2.Cu	copper		0.035 mm		1	0
Dielectric 3	prepreg	FR408-HR	0.11 mm	FR4 natural	3.69	0.0091
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

Sheet:

File: imu-stamp.kicad\_pcb

Title:

Size: A4

Date:

KiCad E.D.A. kicad 7.0.1

Rev:

Id: 1/1



Sheet:  
File: imu-stamp.kicad\_pcb

**Title:**

Size: A4	Date:
KiCad E.D.A.	kicad 7.0.1

Rev:  
Id: 1/1